



Final Product Change Notification

202301023F01 : NBPxx 4x4 Product Family Test Expansion into NXP-ATKL

Note: This notice is NXP Company Proprietary.

Issue Date: Jan 23, 2023 **Effective date:** Apr 23, 2023

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Management summary

Final Test Expansion for the NBPxx Family of devices into the NXP-ATKL test facility.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP is pleased to announce the expansion of final test for the NBPxx Product Family into the NXP-ATKL (Assembly and Test, Kuala Lumpur, Malaysia) test site.

Reason

Expansion of test into the NXP-ATKL final test site for supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment Apr 24, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Feb 22, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
NBP8FD4T1	935408776528	NBP8FD4T1	BPMS 40 - 250kPa	HQFN24FAMWF	SOT1931-1(D)	RFS	No	BLC6
NBP8FD5T1	935410616528	NBP8FD5T1	BPMS SPI	HQFN24FAMWF	SOT1931-1(D)	ASM	No	BLC6
NBP9FD4T1	935410617528	NBP9FD4T1	BPMS SPI PWM	HQFN24FAMWF	SOT1931-1(D)	RFS	No	BLC6
NBP9FD5T1	935420224528	NBP9FD5T1	BPMS SPI PWM Prec Tol	HQFN24FAMWF	SOT1931-1(D)	ASM	No	BLC6